



IN THE CLAIMS

Claims 1-4, 6, 8-18 and 23-32 are pending in this application. Please cancel claims 5 and 7 without prejudice or disclaimer, and amend claim 1 as follows:

1. (Currently Amended) A resin laminate sound insulation board which is a laminated plate, comprising:
 - a foamable resin foamed at a foaming temperature by heating;
 - a shape-formable hard metal plate; and
 - a non-foamable material laminated between said foamable resin and said hard plate, wherein said foamable resin and said non-foamable material are adhered to each other and said non-foamable material are adhered to said hard plate prior to heating and prior to said hard plate being formed to a desired shape, and
 - said foamable resin is heated to a foamed state having a thickness that enhances a rigidity of at least said shaped hard plate.
2. (Previously Presented) A resin laminate sound insulation board which is a laminated plate, comprising:
 - at least a first foamable resin foamed at a first foaming temperature by heating,
 - a second foamable resin foamed at a second foaming temperature by heating,
 - and
 - a shape-formable hard metal plate, wherein the first foamable resin is adhered to the hard plate and the second foamable resin is adhered to the first foamable resin prior to the hard plate being formed to a desired shape, wherein
 - at least one of said first and second foamable resins is heated to a foamed state having a thickness that enhances a rigidity of at least said shaped hard plate.
3. (Previously Presented) The resin laminate sound insulation board according to claim 2, wherein the first foaming temperature of the first foamable resin is different from the second foaming temperature of the second foamable resin.
4. (Previously Presented) The resin laminate sound insulation board according to claim 2, wherein the melting point of the first formable resin is different from that of the second foamable resin.

5. (Canceled).
6. (Previously Presented) The resin laminate sound insulation board according to claim 1, wherein the non-foamable material is a non-foamable resin not foamable by heating.
7. (Canceled)
8. (Previously Presented) The resin laminate sound insulation board according to claim 1, wherein said foamable resin is heated at a temperature lower than the foaming temperature, and thermally fused to the hard plate to form the laminated plate.
9. (Previously Presented) The resin laminate sound insulation board according to claim 6, wherein said non-foamable resin is heated at a temperature lower than said foaming temperature, and thermally fused to the foamable resin to form the laminated plate.
10. (Previously Presented) The resin laminate sound insulation board according to claim 6, wherein a melting point of said non-foamable resin is higher than a melting point of said foamable resin.
11. (Previously Presented) The resin laminate sound insulation board according to claim 6, wherein said non-foamable resin is a thermosetting resin or a thermoplastic resin.
12. (Previously Presented) The resin laminate sound insulation board according to claim 1, wherein said foamable resin is a thermosetting resin or a thermoplastic resin.
13. (Previously Presented) The resin laminate sound insulation board according to claim 11, wherein a melting point of said thermoplastic resin is 100-260° C.
14. (Previously Presented) The resin laminate sound insulation board according to claim 12 wherein a melting point of said thermoplastic resin is 100-260° C.

15. (Previously Presented) The resin laminate sound insulation board according to claim 1, wherein said foamable resin is formed from a mixture of a foaming agent that is decomposable by heating with a resin.
16. (Previously Presented) The resin laminate sound insulation board according to claim 1, wherein said foaming temperature is set to 120-300° C.
17. (Previously Presented) A resin laminate sound insulation board according to claim 1, wherein the foamed resin laminate sound insulation board according is heated to said foaming temperature to make the foamable resin into a foamed resin.
18. (Previously Presented) The resin laminate sound insulation board according to claim 17, wherein said foamable resin is made into the foamed resin by heating after the foamed resin laminate sound insulation board is worked into a prescribed shape.
19. (Withdrawn) A method for manufacturing a foamed resin laminate sound insulation board comprising: a laminating process for laminating at least an unfoamed foamable resin to be foamed at a foaming temperature by heating and a hard plate; and a process for integrating the laminate of said foamable resin and the hard plate at a temperature lower than the foaming temperature of the foamable resin.
20. (Withdrawn) The method for manufacturing a foamed resin laminate sound insulation board according to claim 19 comprising the laminating process, said laminate integrating process, and a heating process for heating the laminate to the foaming temperature of said foamable resin to make said foamable resin to a foamed resin.
21. (Withdrawn) The method for manufacturing a foamed resin laminate sound insulation board according to claim 20 comprising said laminating process, the laminate integrating process, a molding process for working the laminate into a prescribed shape in the integrated state, and said heating process.

22. (Withdrawn) The method for manufacturing a foamed resin laminate sound insulation board according to claim 20 wherein said heating process is carried out simultaneously with a heating treatment for baking finish.
23. (Previously Presented) The resin laminate sound insulation board according to claim 2, wherein at least one of said first and second foamable resins is heated at a temperature lower than the corresponding first or second foaming temperature, and thermally fused to the hard plate or first foamable resin, respectively.
24. (Previously Presented) The resin laminate sound insulation board according to claim 7, wherein said non-foamable resin is heated at a temperature lower than said foaming temperature, and thermally fused to the hard plate.
25. (Previously Presented) The resin laminate sound insulation board according to claim 7, wherein the melting point of said non-foamable resin is higher than the melting point of said foamable resin.
26. (Previously Presented) The resin laminate sound insulation board according to claim 7, wherein said non-foamable resin is a thermosetting resin or a thermoplastic resin.
27. (Previously Presented) The resin laminate sound insulation board according to claim 2, wherein said foamable resin is a thermosetting resin or a thermoplastic resin.
28. (Previously Presented) The resin laminate sound insulation board according to claim 26, wherein a melting point of said thermoplastic resin is 100-260° C.
29. (Previously Presented) The resin laminate sound insulation board according to claim 27, wherein a melting point of said thermoplastic resin is 100-260° C.
30. (Previously Presented) The resin laminate sound insulation board according to claim 2, wherein said foamable resin is formed from a mixture of a foaming agent that is decomposable by heating with a resin.

31. (Previously Presented) The resin laminate sound insulation board according to claim 2, wherein said foaming temperature is set to 120-300° C.
32. (Previously Presented) A resin laminate sound insulation board according to claim 2, wherein the foamed resin laminate sound insulation board is heated to said foaming temperature to make the foamable resin into a foamed resin.